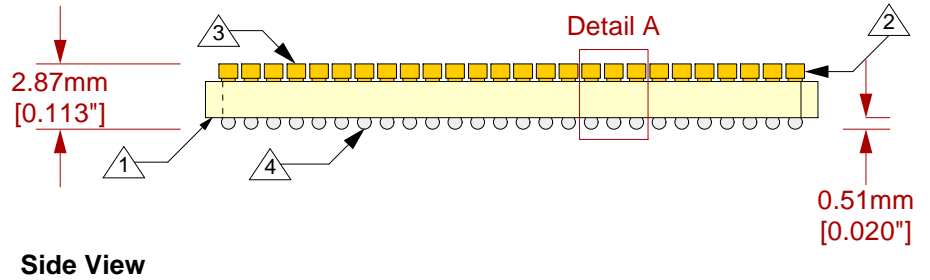
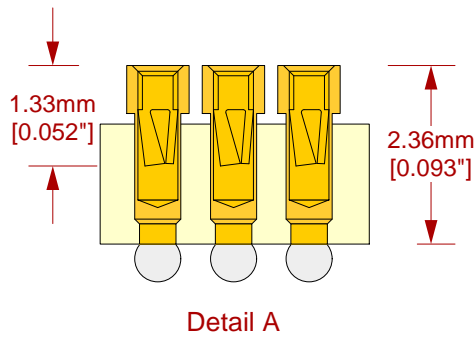
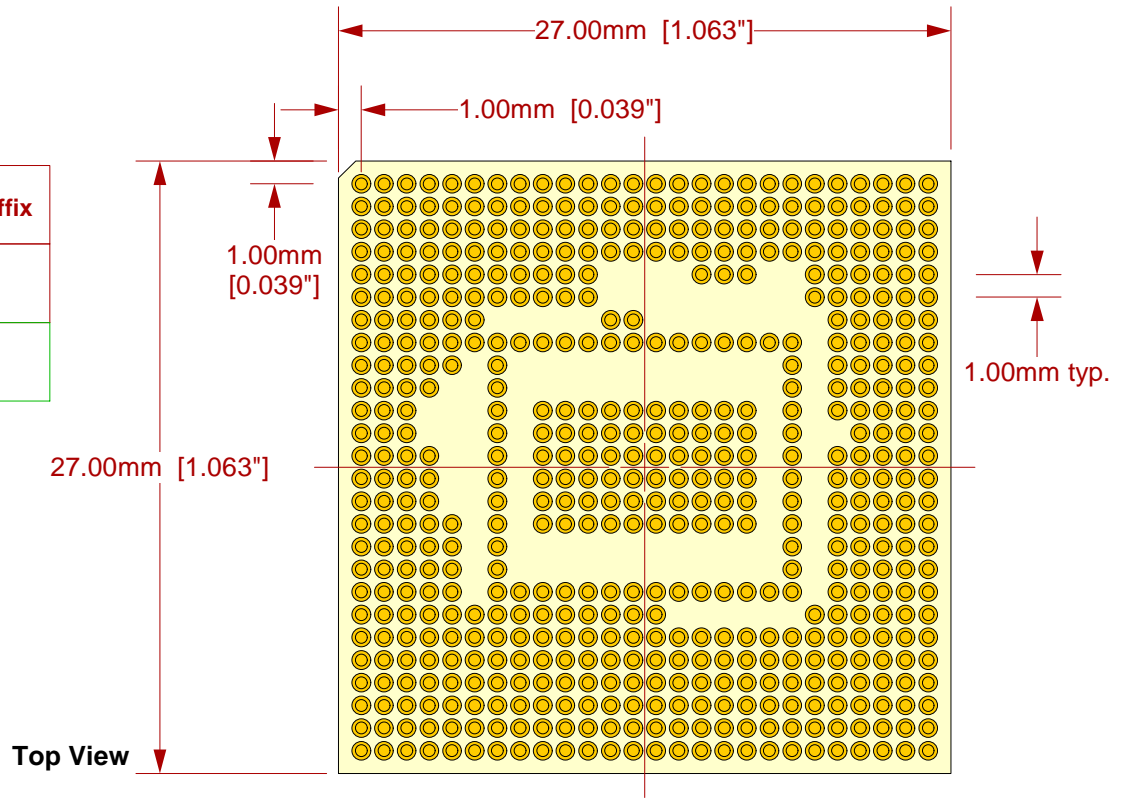


# Patent Pending

## Ordering Information:

Solder Ball Alloy	Part Number Suffix
Sn63Pb37	-42
Sn96.5Ag3.0Cu0.5	-42F*

\*RoHS Compliant



- ① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. (RoHS)
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- ③ Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- ④ Solder Balls: See the table

## CONTACT DATA

Accepts 0.20mm - 0.33mm Diameter pins

3-finger

37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)

30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)

20/17 gram, extraction force (with 0.254mm/0.203mm dia. pin)



## Description: Giga-snaP BGA SMT Foot

550 position (1.0mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

## SF-BGA550A-B-42(F) Drawing

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 Tele: (800) 404-0204  
 www.ironwoodelectronics.com

Status: Released

Scale: 4:1

Rev: A

Drawing: E. Smolentseva

Date: 1/17/12

File: SF-BGA550A-B-42(F) Dwg

Modified:

